

ABSTRACT OF THE DISCLOSURE

An electrode on a main surface of a module board, to which an emitter electrode of a semiconductor chip formed with a switching element of a power supply control circuit that supplies a power supply voltage to amplifier circuit parts of a power module of a digital cellular phone is electrically connected to a wiring in an internal layer of the module board through a plurality of viaholes. Further, the wiring CL1 is electrically connected to an electrode for the supply of the power supply voltage, which is provided on a back surface of the module board. Accordingly, an output characteristic of the semiconductor device is improved.